

**PRODUCT / PROCESS CHANGE INFORMATION**

**1. PCI basic data**

<b>1.1 Company</b>		STMicroelectronics International N.V
<b>1.2 PCI No.</b>	AMS/19/11313	
<b>1.3 Title of PCI</b>	New assembly process sequence in SOIC 18 lead for devices assembled in CIRTEK including single DTFS tool (Deflash, Trim, Form and Singulation)	
<b>1.4 Product Category</b>	See product list	
<b>1.5 Issue date</b>	2019-02-03	

**2. PCI Team**

<b>2.1 Contact supplier</b>	
<b>2.1.1 Name</b>	ROBERTSON HEATHER
<b>2.1.2 Phone</b>	+1 8475853058
<b>2.1.3 Email</b>	heather.robertson@st.com
<b>2.2 Change responsibility</b>	
<b>2.2.1 Product Manager</b>	Lorenzo NASO
<b>2.1.2 Marketing Manager</b>	Marcello SAN BIAGIO
<b>2.1.3 Quality Manager</b>	Sergio Tommaso SPAMPINATO

**3. Change**

<b>3.1 Category</b>	<b>3.2 Type of change</b>	<b>3.3 Manufacturing Location</b>
Methods	Process flow chart: Revision change in Process (process technology, sawing, die attach, plasma, capillary, marking, packing, labelling, transportation, etc..)	CIRTEK Electronics Corp., Philippines

**4. Description of change**

	<b>Old</b>	<b>New</b>
<b>4.1 Description</b>	SOIC 18L process with separated process step/tools for Defflash/Trim and Form/Singulation	1) SOIC 18L assembly process with separated process step/tools for Defflash/Trim and Form/Singulation 2) SOIC 18L assembly process with Deflash/Trim/ Form/ Singulation -progressive process tool
<b>4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?</b>	No impact	

**5. Reason / motivation for change**

<b>5.1 Motivation</b>	Progressing on the activities related to our service continuous improvement, ST is glad to announce the introduction of a new assembly process sequence for ST SOIC 18 leads devices assembled in CIRTEK, Philippines as additional option to increase the volume loading in assembly line.
<b>5.2 Customer Benefit</b>	SERVICE IMPROVEMENT

**6. Marking of parts / traceability of change**

<b>6.1 Description</b>	No change in marking, traceability guaranteed by new dedicated genealogy (Raw Line and Finished Good codes)
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**7. Timing / schedule**

<b>7.1 Date of qualification results</b>	2019-01-17
<b>7.2 Intended start of delivery</b>	2019-03-01
<b>7.3 Qualification sample available?</b>	Upon Request

**8. Qualification / Validation**

<b>8.1 Description</b>	11313 Cirtek SOIC18L new flow with DTFS tool_report.pdf
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8.2 Qualification report and qualification results	Available (see attachment)	Issue Date	2019-02-03
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<b>9. Attachments (additional documentations)</b>
11313 Public product.pdf 11313 Cirtek SOIC18L new flow with DTFS tool_report.pdf

<b>10. Affected parts</b>		
<b>10. 1 Current</b>		<b>10.2 New (if applicable)</b>
<b>10.1.1 Customer Part No</b>	<b>10.1.2 Supplier Part No</b>	<b>10.1.2 Supplier Part No</b>
	M41T83RMY6F	
	M41T83SMY6F	
	M41T83ZMY6F	
	M41T93RMY6F	
	M41T93SMY6F	
	M41T93ZMY6F	
M41T81SMY6F	M41T81SMY6F	

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## Public Products List

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**PCI Title :** New assembly process sequence in SOIC 18 lead for devices assembled in CIRTEK including single DTFS tool (Deflash, Trim, Form and Singulation)

**PCI Reference :** AMS/19/11313

**Subject :** Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

M41T83ZMY6F	M41T93SMY6F	M41T93RMY6F
M41T83RMY6F	M41T83SMY6F	M41T93ZMY6F
M41T81SMY6F		



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